



VOLTAGE PROTECTION FOR 2-, 3-, OR 4-CELL Lion BATTERIES (2 PROTECTION)

FEATURES

- 2-, 3-, or 4-Cell Secondary Protection
- Low Power Consumption $I_{CC} < 2 \mu A$ [VCELL_(ALL) $< V_{(PROTECT)}$]
- High Accuracy Over Sense Voltage:
 - bq29400: 4.35 V ±25 mV
 - bq29400A: 4.40 V ±25 mV
 - bq29401: 4.45 V ±25 mV
 - bq29405: 4.65 V ±25 mV
- Prefixed Protection Threshold Voltage
- Programmable Delay Time
- High Power Supply Ripple Rejection
- Stable During Pulse Charge Operation

APPLICATIONS

- 2nd Level Protection in Lion Battery Packs in
 - Notebook PCs
 - Portable Instrumentation
 - Medical and Test Equipment

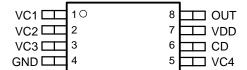
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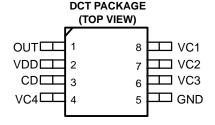
The bq29400, bq29400A, bq29401, and bq29405 are BiCMOS secondary protection ICs for 2-, 3-, or 4-cell Lithium-lon battery packs that incorporate a high-accuracy precision over voltage detection circuit. They include a programmable delay circuit for over voltage detection time.

FUNCTION

Each cell in a multiple cell pack is compared to an internal reference voltage. If one cell reaches an overvoltage condition, the protection sequence begins. The bq2940x device starts charging an external capacitor through the CD pin. When the CD pin voltage reaches 1.2 V, the OUT pin changes from a low level to a high level.

PW PACKAGE (TOP VIEW)





ORDERING INFORMATION

т	V	PACKAGE						
T _A	V(PROTECT)	MSOP (DTC)	SYMBOL	TSSOP (PW)(1)	SYMBOL			
–25°C to 85°C	4.35 V	bq29400DCT3	CIQ	bq29400PW	2400			
	4.40 V	bq29400ADCT3	CIT	Not Available	-			
	4.45 V	bq29401DCT3	CIR	bq29401PW	2401			
	4.65 V	bq29405DCT3	CIS	Not Available	-			

(1) The bq29400, bq29400A, bq29401, and bq29405 are available taped and reeled. Add an R suffix to the device type (e.g., bq29400PWR) to order tape and reel version.



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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range unless otherwise noted (1)(2)

		UNIT
Supply voltage range	(VDD)	-0.3 V to 28 V
Innut voltage range	(VC1, VC2, VC3, VC4)	-0.3 V to 28 V
Input voltage range	(VC1 to VC2, VC2 to VC3, VC3 to VC4, VC4 to GND)	-0.3 V to 8 V
Output valtage renge	(OUT)	-0.3 V to 28 V
Output voltage range	(CD)	-0.3 V to 28 V
Continuous total power	r dissipation	See Dissipation Rating Table
Storage temperature ra	ange, T _{stg}	-65°C to 150°C
Lead temperature (solo	dering, 10 sec)	300°C

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

PACKAGE DISSIPATION RATINGS

PACKAGE	T _A ≤ 25°C POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING
DCT	412 mW	3.3 mW/°C	264 mW	214 mW
PW	525 mW	4.2 mW/°C	336 mW	273 mW

RECOMMENDED OPERATING CONDITIONS

			MIN	NOM	MAX	UNIT
V_{DD}	Supply Voltage		4.0		25	V
VI	lanut valtaga ranga	VC1, VC2, VC3, VC4	0		V_{DD}	
	Input voltage range	VCn - VC(n+1), (n=1, 2, 3), VC4-GND	0		5.0	V
t _{d(CD)}	Delay time capacitance			0.22		μF
R _{IN}	Voltage-monitor filter resistance		100	1k		Ω
C _{IN}	Voltage-monitor filter capacitance		0.01	0.1		μF
R_{VD}	Supply-voltage filter resistance		0		100	Ω
C _{VD}	Supply-voltage filter capacitance			0.1		μF
T _A	Operating ambient temperature ra	nge	-25		85	°C

⁽²⁾ All voltages are with respect to ground of this device except the differential voltage of VC1-VC2, VC2-VC3, VC3-VC4 and VC4-GND.



ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range, $T_A = 25^{\circ}C$ (unless otherwise noted)⁽¹⁾

PARAMETER			TEST CONDITION	MIN	NOM	MAX	UNIT
V Over veltage detection accuracy				25	35	mV	
V _(OA)	Over voltage detection accura	асу	$T_A = -20$ °C to 85°C		25	50	IIIV
		bq29400			4.35		
\/	Over voltage detection	bq2940A			4.40		V
V _(PROTECT)	voltage ⁽¹⁾	bq29401			4.45		V
		bq29405			4.65		•
V _{hys}	Over voltage detection hysteresis ⁽¹⁾				300		mV
I	Input current		V2, V3 , VC4 inputVC1 = VC2 = VC3 = VC4 = 3.5 V (see Figure 1)			±0.3	μΑ
t _{D1}	Over voltage detection delay time		CD = 0.22 µF	1.0	1.5	2.0	S
I _(CD_dis)	CD GND clamp current		CD = 1 V	5	12		μA
	Supply current		VC1 = VC2 = VC3 = VC4 = 3.5 V (see Figure 1)		2.0	3.0	
I _{CC}			VC1 = VC2 = VC3 = VC4 = 2.3 V (see Figure 1)	1.5		2.5	μA
V _(OUT)	OUT pin drive voltage		VC1 = VC2 = VC3 = VC4 = 4.7 V, IOH = 0 mA		7		V
I _{OH}	High-level output current		OUT = 3V, VC1 = VC2 = VC3 = VC4 = 4.7 V	-1			mA
I _{OL}	Low-level output current		OUT = 0.1 V VC1 = VC3 = VC4 = 3.5 V	5			μΑ

(1) Levels of the over-voltage detection and the hysteresis can be adjusted. For assistance contact Texas Instruments sales representative.

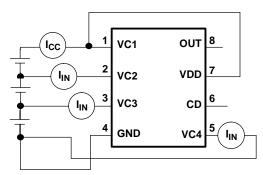


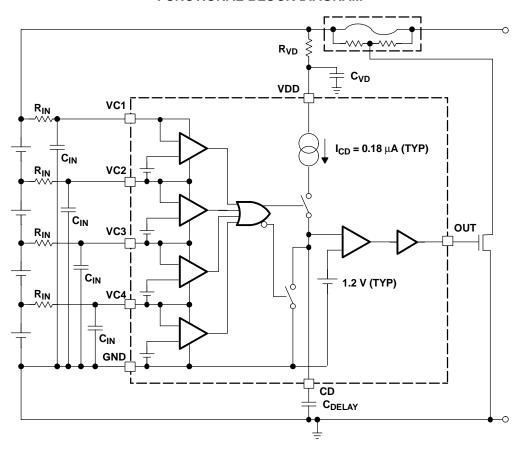
Figure 1. I_{CC}, I_{IN} Measurement (TSSOP Package)

Terminal Functions

TERMINAL No.		lo.	
MSOP (DTC)	TSSOP (PW)	NAME	DESCRIPTION
8	1	VC1	Sense voltage input for most positive cell
7	2	VC2	Sense voltage input for second most positive cell
6	3	VC3	Sense voltage input for third most positive cell
5	4	GND	Ground pin
4	5	VC4	Sense voltage input for least positive cell
3	6	CD	An external capacitor is connected to determine the programmable delay time
2	7	VDD	Power supply
1	8	OUT	Output



FUNCTIONAL BLOCK DIAGRAM



OVERVOLTAGE PROTECTION

When one of the cell voltages exceeds $V_{(PROTECT)}$, an internal current source begins to charge the capacitor, $C_{(DELAY)}$, connected to the CD pin. If the voltage at the CD pin, V_{CD} , reaches 1.2 V, the OUT pin is activated and transitions high. An externally connected NCH FET is activated and blows the external fuse in the positive battery rail, see Figure 1.

If all cell voltages fall below $V_{(PROTECT)}$ before the voltage at pin CD reaches 1.2 V, the delay time does not run out. An internal switch clamps the CD pin to GND and discharges the capacitor, $C_{(DELAY)}$, and secures the full delay time for the next occurring overvoltage event.

Once the pin OUT is activated, it transitions back from high to low after all battery cells reach V_(PROTECT) - V_{hys.}

DELAY TIME CALCULATION

The delay time is calculated as follows:

$$t_{d} = \frac{\left[1.2 \text{ V} \times \text{C}_{(DELAY)}\right]}{\text{I}_{CD}}$$
$$C_{(DELAY)} = \frac{\left[t_{d} \times \text{I}_{CD}\right]}{1.2 \text{ V}}$$

Where $I_{(CD)} = CD$ current source = 0.18 μ A



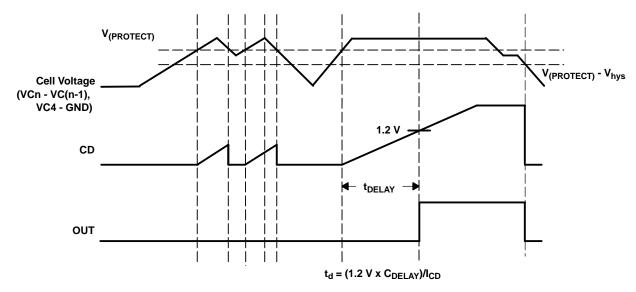


Figure 2. Timing for Overvoltage Sensing



APPLICATION INFORMATION

BATTERY CONNECTIONS

The following diagrams show the TSSOP package device in different cell configurations.

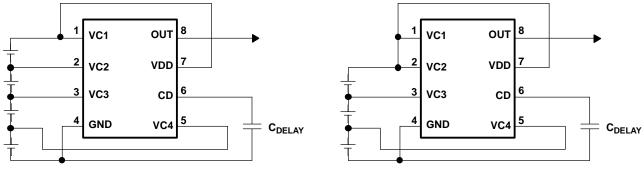


Figure 3. 4-Series Cell Configuration

Figure 4. 3-Series Cell Configuration (Connect together VC1 and VC2)

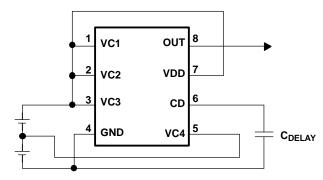


Figure 5. 2-Series Cell Configuration (Connect together VC1, VC2, and VC3)

CELL CONNECTIONS

To prevent incorrect output activation the following connection sequences must be used.

4-Series Cell Configuration

- $VC1(=VDD) \rightarrow VC2 \rightarrow VC3 \rightarrow VC4 \rightarrow GND$ or
- GND \rightarrow VC4 \rightarrow VC3 \rightarrow VC2 \rightarrow VC1(=VDD)

3-Series Cell Configuration

- $VC1(=VC2=VDD) \rightarrow VC3 \rightarrow VC4 \rightarrow GND$ or
- GND \rightarrow VC4 \rightarrow VC3 \rightarrow VC1(=VC2=VDD)

2-Series Cell Configuration

- $VC1(=VC2=VC3=VDD) \rightarrow VC4 \rightarrow GND$ or
- GND \rightarrow VC4 \rightarrow VC1(=VC2=VC3=VDD)





i.com 18-Mar-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	n MSL Peak Temp ⁽³⁾
BQ29400ADCT3	ACTIVE	SM8	DCT	8	3000	Pb-Free (RoHS)	CU SNBI	Level-1-250C-UNLIM
BQ29400ADCT3R	ACTIVE	SM8	DCT	8	3000	TBD	Call TI	Call TI
BQ29400PW	ACTIVE	TSSOP	PW	8	150	TBD	CU NIPDAU	Level-1-220C-UNLIM
BQ29400PWR	ACTIVE	TSSOP	PW	8	2000	TBD	CU NIPDAU	Level-1-220C-UNLIM
BQ29401DCT	PREVIEW	SM8	DCT	8		TBD	Call TI	Call TI
BQ29401DCTR	PREVIEW	SM8	DCT	8	3000	TBD	Call TI	Call TI
BQ29401PW	ACTIVE	TSSOP	PW	8	150	TBD	CU NIPDAU	Level-1-220C-UNLIM
BQ29401PWR	ACTIVE	TSSOP	PW	8	2000	TBD	CU NIPDAU	Level-1-220C-UNLIM
BQ29405DCT3	ACTIVE	SM8	DCT	8	3000	Pb-Free (RoHS)	CU SNBI	Level-1-250C-UNLIM
BQ29405DCT3R	PREVIEW	SM8	DCT	8	3000	TBD	Call TI	Call TI

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

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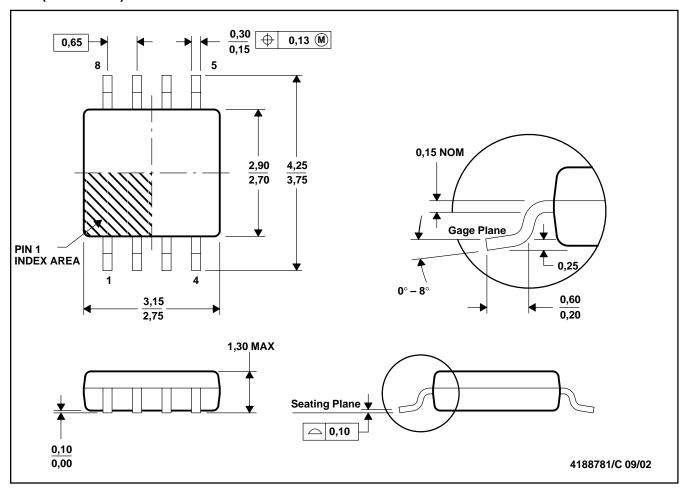
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DCT (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion
- D. Falls within JEDEC MO-187 variation DA.

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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